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(54) **SEMICONDUCTOR PACKAGE HAVING  
ALIGNMENT PATTERN**

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**ABSTRACT**

A semiconductor package includes a substrate including an upper pad and an alignment pad on an upper surface thereof, a first bonding pad disposed on the upper pad, the first bonding pad including a first trench extending in one direction on an upper surface thereof, at least one first alignment pattern disposed on the alignment pad and disposed to be adjacent to the first bonding pad, a semiconductor chip disposed on the substrate, and a first bonding wire connecting the semiconductor chip to the first bonding pad, wherein the at least one first alignment pattern is aligned with the first trench in a direction in which the first trench extends, and the first bonding wire contacts the first bonding pad and partially fills an inner wall of the first trench.

